Ultra-Low Power and High Speed SRAM for Mobile Applications Using Single Poly-Si Gate 90nm CMOS Technology

K. Koh, B.J. Hwang, G.H.Han, K.H. Kwak, Y.S.Son, J.H. Jang, H.S. Kim, D. Park, Kinam Kim ATD team, R&D Center, Samsung Electronics Co., Ltd. Kiheung-Eup, Yongin-City, Kyungki-Do, Korea (ROK), 449-711 Phone:+ 82-31-209-2096, Fax:+ 82-31-209-3274 E-mail:kkoh7@samsung.co.kr

ABSTRACT

High speed and ultra-low power SRAM using single gate CMOS technology was developed. The drive currents of NMSOFET and PMOSFET were 410μ A/ μ m and 205μ A/ μ m, respectively. The random access time of 17ns at 1.65V operation voltage was achieved for the first time in low power application by the reduction of loading capacitance. Standby current was less than 15 μ A/chip. The highly manufacturable compact cell of 0.84 μ m² area was integrated using PR (photo resist) flow technology and novel contact layout.